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Intevac to Present its Work on Fan-Out Packaging at SEMICON Korea 2018 Technology Symposium

SANTA CLARA, Calif.--(BUSINESS WIRE)-- Intevac, Inc. (Nasdaq: IVAC), a leading supplier of thin-film processing systems, today announced its participation in the SEMICON Korea 2018 Electropackage System and Interconnect Product Technical Symposium. The company will present a technical paper on its "Ion Beam Source for RDL Pre-Clean in Fan-Out Wafer and Fan-Out Panel Level Packaging" at 4:15pm Thursday afternoon, February 1st, 2018, in Seoul, Korea, at the COEX exhibition center.

Semiconductor device packaging technology in general, and fan-out wafer-level packaging (FOWLP) / fan-out panel-level packaging (FOPLP) technology in particular, is being driven by the strong cost advantages these advanced packaging technologies offer over the expense of implementing continued Moore's Law progress for sub-10nm semiconductor IC process nodes. Fan-out packaging provides for increased I/O (Input/Output) density for a given semiconductor device while simultaneously supporting smaller die sizes, thereby reducing the amount of space integrated circuit content occupies in handheld consumer electronic products, such as smartphones, wearables, and Internet of Things (IoT) devices.

The INTEVAC MATRIX[®] is a high-productivity, substrate-independent thin-film processing platform that is well-positioned for multiple fan-out packaging applications. The MATRIX Physical Vapor Deposition (PVD) system offers a much-reduced cost of ownership (COO) over the current PVD process tools being used for Redistribution Layer (RDL) barrier/seed layer applications, and also offers the flexibility to run multiple substrates on the same system, from wafer-level (round) substrates to panel-level (square or rectangular) substrates, which today are up to 600mm in diameter.

In addition to the SEMICON Korea 2018 presentation, Intevac's other recent technical papers on advanced packaging processes developed on the MATRIX were featured at IWLPC 2017 in San Jose, CA; EPTC 2017 in Singapore; and at SEMICON Japan 2017 in Tokyo. Copies of these papers are available upon request.

About SEMICON Korea

Since SEMICON Korea was kicked off in 1987, it has become one of the biggest exhibitions in the Korean semiconductor industry. The number of total attendees in 2018 is estimated at 40,000. SEMICON global trade shows, organized by SEMI, are held in 8 countries where the semiconductor industry is flourishing: Korea, USA, China, Japan, Taiwan and other countries.

The SEMI Technology Symposium (STS) 2018, held in conjunction with SEMICON Korea 2018, will provide a dynamic agenda of sessions and presentations on a wide variety of subjects in the area of next-generation semiconductor manufacturing. Topics covered include: Advanced Lithography, Interconnection & Advanced Processes, Devices, Plasma Science and Etching, Contamination-free Manufacturing and CMP Technology, and Electropackage Systems and Interconnects.

For more information visit www.semiconkorea.org/en/.

About Intevac

Intevac was founded in 1991 and has two businesses: Thin-film Equipment and Photonics.

In our Thin-film Equipment business, we are a leader in the design and development of high-productivity, thin-film processing systems. Our production-proven platforms are designed for high-volume manufacturing of substrates with precise thin film properties, such as the hard drive media, display cover panel, and solar photovoltaic markets we serve currently.

In our Photonics business, we are a recognized leading developer of advanced high-sensitivity digital sensors, cameras and systems that primarily serve the defense industry. We are the provider of integrated digital imaging systems for most U.S. military night vision programs.

For more information call 408-986-9888, or visit the Company's website at www.intevac.com.

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